

Errata

# CC35xxE SimpleLink 2.4GHz and 5GHz Dual-Band Wi-Fi 6 and Bluetooth Low Energy Wireless MCU

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## ABSTRACT

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## 1 Advisories Matrices

**Table 1-1. Advisories Matrix**

MODULE	DESCRIPTION	SILICON REVISIONS AFFECTED
		2.0
RADIO	<a href="#">Advisory RADIO_01</a> - Use at ambient temperatures >85C potentially causes device heating that exceeds maximum operating conditions	X
RADIO	<a href="#">Advisory RADIO_02</a> - 5GHz RF maximum input level reduced 3dB prior to association	X
ADC	<a href="#">Advisory ADC_01</a> - When operating the ADC in scheduled periodic conversion mode, ad-hoc conversions should not be performed	X

## 2 Nomenclature, Package Symbolization, and Revision Identification

### 2.1 Device and Development-Support Tool Nomenclature

To designate the stages in the product development cycle, TI assigns prefixes to the part numbers of all microprocessors (MPUs) and support tools. Each device has one of three prefixes: X, P, or null (no prefix) (for example, *CC3501E* or *CC3551E*). Texas Instruments recommends two of three possible prefix designators for its support tools: TMDX and TMDS. These prefixes represent evolutionary stages of product development from engineering prototypes (TMDX) through fully qualified production devices and tools (TMDS).

Device development evolutionary flow:

- X** Experimental device that is not necessarily representative of the final device's electrical specifications and may not use production assembly flow.
- P** Prototype device that is not necessarily the final silicon die and may not necessarily meet final electrical specifications.
- null** Production version of the silicon die that is fully qualified.

Support tool development evolutionary flow:

- TMDX** Development-support product that has not yet completed Texas Instruments internal qualification testing.
- TMDS** Fully-qualified development-support product.

X and P devices and TMDX development-support tools are shipped against the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

Production devices and TMDS development-support tools have been characterized fully, and the quality and reliability of the device have been demonstrated fully. TI's standard warranty applies.

Predictions show that prototype devices (X or P) have a greater failure rate than the standard production devices. Texas Instruments recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

### 2.2 Devices Supported

This document supports the following devices:

- [CC3501E](#)
- [CC3551E](#)

### 2.3 Package Symbolization and Revision Identification

Figure 2-1 and Table 2-1 describe package symbolization and device revision codes.

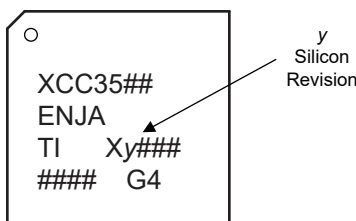


Figure 2-1. Package Symbolization

Table 2-1. Revision Identification

DEVICE REVISION CODE (y)	SILICON REVISION
(empty)	PG1.0
B	PG2.0

The device marking includes the part number XCC35##, where the ## denote the exact part number, either CC3500, CC3501, CC3550, or CC3551. Please see data sheets for device identification.

The device marking also includes the Silicon revision in the form Xy####. The "X" marks pre-production silicon, and the "y" denotes the exact silicon revision, PG1 or PG2. The lack of the "y" indicates PG1. For example, "X458" is a possible marking for PG1, because after the "X" there is no "B" (marking PG2) before the next three characters (in this case "458").

### **3 Silicon Revision 2.0 Advisories**

The following advisories are known design exceptions to functional specifications. Advisories are numbered in the order in which the advisory was added to this document. Some advisory numbers are removed in future revisions of this document because the design exception was fixed or documented in the device-specific data manual or technical reference manual. When items are deleted, the remaining advisory numbers are not re-sequenced.

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<b>Advisory</b> <b>RADIO_01</b>	<b><i>Use at ambient temperatures &gt;85C potentially causes device heating that exceeds maximum operating conditions</i></b>
<b>Revisions Affected</b>	PG2.0
<b>Details</b>	The RF core does not limit radio activity at $105\text{C} > T_A > 85\text{C}$ . Continuous operation of the radio at temperatures $>85\text{C}$ potentially causes the device to exceed maximum ratings.
<b>Workaround</b>	Limit transmission from the host or disable Wi-Fi and BLE functions when ambient temperature rises above 85 C.

**Advisory**  
**RADIO\_02**      ***5GHz RF maximum input level reduced 3dB prior to association***

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**Revisions Affected**      PG2.0

**Details**      Prior to association in the 5GHz band packets can only be decoded if they are received with a maximum input power of 3dB less than that specified in the datasheet. After association this limitation does not apply.

**Workaround**      Limit maximum input power when operating in 5GHz band so it is 3dB less than the Maximum Input Level specified in the datasheet

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**Advisory ADC\_01** *When operating the ADC in scheduled periodic conversion mode, ad-hoc conversions should not be performed*


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**Revisions Affected** PG2.0

**Details** When operating the ADC in scheduled periodic conversion mode, ad-hoc conversions should not be performed or the periodic conversion may be corrupted.

**Workaround** Scheduled periodic conversions should be stopped in order to perform an ad-hoc conversion. Scheduled periodic conversions can be restarted after the ad-hoc conversion.

#### 4 Trademarks

All trademarks are the property of their respective owners.

#### 5 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

DATE	REVISION	NOTES
December 2025	*	Initial Release



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